

## PSMN7R5-30MLD

N-channel 30 V, 7.5 m $\Omega$  logic level MOSFET in LFPAK33 using NextPowerS3 Technology

11 August 2015

Product data sheet

### 1. General description

Logic level gate drive N-channel enhancement mode MOSFET in LFPAK33 package. NextPowerS3 portfolio utilising Nexperia's unique "SchottkyPlus" technology delivers high efficiency, low spiking performance usually associated with MOSFETs with an integrated Schottky or Schottky-like diode but without problematic high leakage current. NextPowerS3 is particularly suited to high efficiency applications at high switching frequencies.

#### 2. Features and benefits

- Ultra low Q<sub>G</sub>, Q<sub>GD</sub> and Q<sub>OSS</sub> for high system efficiency, especially at higher switching frequencies
- Superfast switching with soft-recovery; s-factor > 1
- Low spiking and ringing for low EMI designs
- Unique "SchottkyPlus" technology; Schottky-like performance with < 1 μA leakage at 25 °C
- Optimised for 4.5 V gate drive
- Low parasitic inductance and resistance
- High reliability clip bonded and solder die attach Mini Power SO8 package; no glue, no wire bonds, gualified to 175 °C
- Exposed leads for optimal visual solder inspection

### 3. Applications

- On-board DC-to-DC solutions for server and telecommunications
- Secondary-side synchronous rectification in telecommunication applications
- Voltage regulator modules (VRM)
- Point-of-Load (POL) modules
- Power delivery for V-core, ASIC, DDR, GPU, VGA and system components
- Brushed and brushless motor control

#### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>DS</sub>	drain-source voltage	25 °C ≤ T <sub>j</sub> ≤ 175 °C	-	-	30	V
I <sub>D</sub>	drain current	T <sub>mb</sub> = 25 °C; V <sub>GS</sub> = 10 V; <u>Fig. 2</u>	-	-	57	Α
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; <u>Fig. 1</u>	-	-	45	W



Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Tj	junction temperature			-55	-	175	°C
Static charact	Static characteristics						
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS}$ = 4.5 V; $I_D$ = 10 A; $T_j$ = 25 °C; Fig. 10		-	8.2	10.3	mΩ
		$V_{GS}$ = 10 V; $I_D$ = 15 A; $T_j$ = 25 °C; Fig. 10		-	6.3	7.6	mΩ
Dynamic char	acteristics						•
$Q_{GD}$	gate-drain charge	V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 15 A; V <sub>DS</sub> = 15 V; Fig. 12; Fig. 13		-	1.7	2.5	nC
Q <sub>G(tot)</sub>	total gate charge	V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 15 A; V <sub>DS</sub> = 15 V; Fig. 12; Fig. 13		-	5.8	8.8	nC
Source-drain diode							,
S	softness factor	$I_S$ = 15 A; $V_{GS}$ = 0 V; $dI_S/dt$ = -100 A/ $\mu$ s; $V_{DS}$ = 15 V; <u>Fig. 16</u>		-	1.2	-	

## 5. Pinning information

**Table 2.** Pinning information

Tubic 2.	9	IIIIOIIIIatioii		
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source		D
2	S	source		
3	S	source		G T T
4	G	gate		mbb076 S
mb	D	mounting base; connected to drain	LFPAK33 (SOT1210)	

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PSMN7R5-30MLD	LFPAK33	Plastic single ended surface mounted package (LFPAK33); 8 leads	SOT1210

## 7. Marking

Table 4. Marking codes

Type number		Marking code	
PSMN7R5-30MLD		7D530L	
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## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>DS</sub>	drain-source voltage	25 °C ≤ T <sub>j</sub> ≤ 175 °C		-	30	V
$V_{DGR}$	drain-gate voltage	25 °C ≤ $T_j$ ≤ 175 °C; $R_{GS}$ = 20 kΩ		-	30	V
$V_{GS}$	gate-source voltage			-20	20	V
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; <u>Fig. 1</u>		-	45	W
I <sub>D</sub>	drain current	V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 25 °C; <u>Fig. 2</u>		-	57	Α
		V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 100 °C; <u>Fig. 2</u>		-	40	Α
I <sub>DM</sub>	peak drain current	pulsed; $t_p \le 10 \mu s$ ; $T_{mb} = 25 °C$ ; Fig. 3		-	230	Α
T <sub>stg</sub>	storage temperature			-55	175	°C
Tj	junction temperature			-55	175	°C
T <sub>sld(M)</sub>	peak soldering temperature			-	260	°C
Source-dra	in diode					
I <sub>S</sub>	source current	T <sub>mb</sub> = 25 °C		-	38	Α
I <sub>SM</sub>	peak source current	pulsed; $t_p \le 10 \ \mu s$ ; $T_{mb} = 25 \ ^{\circ}C$		-	230	Α
Avalanche	ruggedness					
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	$V_{GS}$ = 10 V; $T_{j(init)}$ = 25 °C; $I_D$ = 15 A; $V_{sup} \le$ 30 V; $R_{GS}$ = 50 $\Omega$ ; unclamped; $t_p$ = 97 $\mu s$	[1]	-	28.3	mJ

<sup>[1]</sup> Protected by 100% test

3 / 13

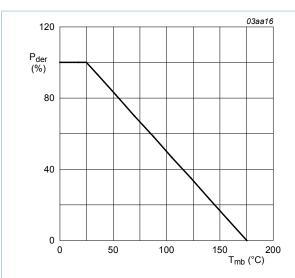


Fig. 1. Normalized total power dissipation as a function of mounting base temperature

$$P_{\textit{der}} = \frac{P_{\textit{tot}}}{P_{\textit{tot}(25^{\circ}\textit{C})}} \times \textbf{100 \%}$$

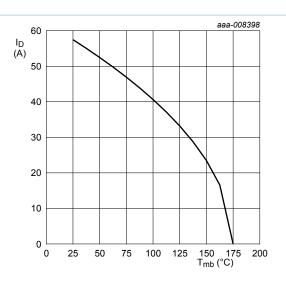


Fig. 2. Continuous drain current as a function of mounting base temperature

$$V_{GS} \ge 10V$$

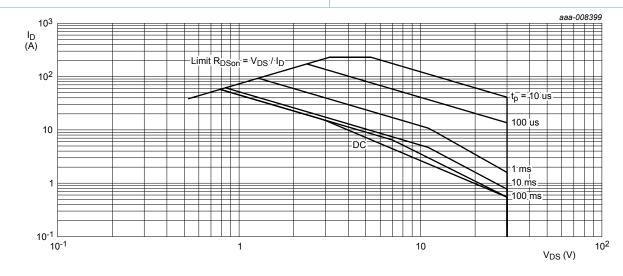


Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

 $T_{mb} = 25^{\circ}C$ ;  $I_{DM}$  is a single pulse

### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	Fig. 4	-	3.1	3.32	K/W

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Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-a)}$	thermal resistance	Fig. 5	-	57	-	K/W
	from junction to ambient	Fig. 6	-	178	-	K/W

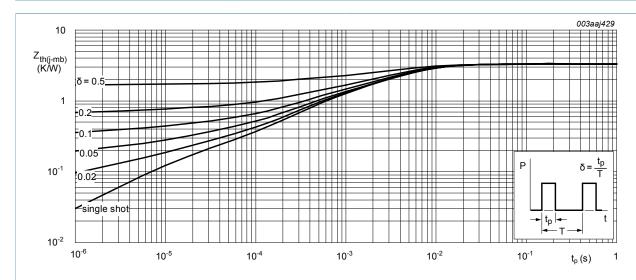


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

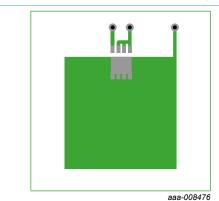


Fig. 5. PCB layout for thermal resistance junction to ambient 1" square pad; FR4 Board; 2oz copper

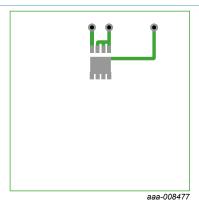


Fig. 6. PCB layout for thermal resistance junction to ambient minimum footprint; FR4 Board; 2oz copper

### 10. Characteristics

Table 7. Characteristics

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Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Static characteristics							
V <sub>(BR)DSS</sub> drain-source	I <sub>D</sub> = 250 μA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		30	-	-	V	
	breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = -55 °C$		27	-	-	V
V <sub>GS(th)</sub>	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ °C}$		1.2	1.7	2.2	V

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Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$\Delta V_{GS(th)}/\Delta T$	gate-source threshold voltage variation with temperature	25 °C ≤ T <sub>j</sub> ≤ 150 °C	-	-3.8	-	mV/K
I <sub>DSS</sub>	drain leakage current	$V_{DS} = 24 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C}$	-	-	1	μΑ
		V <sub>DS</sub> = 24 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 125 °C	-	0.26	-	μA
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 16 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	100	nA
		V <sub>GS</sub> = -16 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	100	nA
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS} = 4.5 \text{ V}; I_D = 10 \text{ A}; T_j = 25 ^{\circ}\text{C};$ Fig. 10	-	8.2	10.3	mΩ
		V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 10 A; T <sub>j</sub> = 150 °C; Fig. 11; Fig. 10	-	-	17	mΩ
		V <sub>GS</sub> = 10 V; I <sub>D</sub> = 15 A; T <sub>j</sub> = 25 °C; Fig. 10	-	6.3	7.6	mΩ
	V <sub>GS</sub> = 10 V; I <sub>D</sub> = 15 A; T <sub>j</sub> = 150 °C; Fig. 11; Fig. 10	-	-	12.5	mΩ	
$R_G$	gate resistance	f = 1 MHz	-	0.25	0.49	Ω
Dynamic ch	aracteristics					
Q <sub>G(tot)</sub> total gate charge	total gate charge	I <sub>D</sub> = 15 A; V <sub>DS</sub> = 15 V; V <sub>GS</sub> = 10 V; Fig. 12; Fig. 13	-	11.3	17	nC
		I <sub>D</sub> = 15 A; V <sub>DS</sub> = 15 V; V <sub>GS</sub> = 4.5 V; Fig. 12; Fig. 13	-	5.8	8.8	nC
		I <sub>D</sub> = 0 A; V <sub>DS</sub> = 0 V; V <sub>GS</sub> = 10 V	-	10.2	-	nC
Q <sub>GS</sub>	gate-source charge	I <sub>D</sub> = 15 A; V <sub>DS</sub> = 15 V; V <sub>GS</sub> = 4.5 V;	-	1.97	-	nC
Q <sub>GS(th)</sub>	pre-threshold gate- source charge	Fig. 12; Fig. 13	-	1.14	-	nC
Q <sub>GS(th-pl)</sub>	post-threshold gate- source charge		-	0.83	-	nC
$Q_{GD}$	gate-drain charge		-	1.7	2.5	nC
V <sub>GS(pl)</sub>	gate-source plateau voltage	I <sub>D</sub> = 15 A; V <sub>DS</sub> = 15 V; <u>Fig. 12</u> ; <u>Fig. 13</u>	-	2.9	-	V
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = 15 V; V <sub>GS</sub> = 0 V; f = 1 MHz;	-	655	982	pF
C <sub>oss</sub>	output capacitance	T <sub>j</sub> = 25 °C; <u>Fig. 14</u>	-	578	867	pF
C <sub>rss</sub>	reverse transfer capacitance		-	50	75	pF
t <sub>d(on)</sub>	turn-on delay time	$V_{DS}$ = 15 V; $R_L$ = 1 $\Omega$ ; $V_{GS}$ = 4.5 V;	-	7.1	-	ns
t <sub>r</sub>	rise time	$R_{G(ext)} = 5 \Omega$	-	10.4	-	ns
t <sub>d(off)</sub>	turn-off delay time		-	8.5	-	ns
t <sub>f</sub>	fall time	1	-	5.5	-	ns

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Q <sub>oss</sub>	output charge	$V_{GS} = 0 \text{ V}; V_{DS} = 15 \text{ V}; f = 1 \text{ MHz};$ $T_j = 25 \text{ °C}$		-	11	-	nC
Source-dra	in diode				- 1	'	
$V_{SD}$	source-drain voltage	$I_S = 10 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C}; Fig. 15$		-	0.82	1.2	V
t <sub>rr</sub>	reverse recovery time	$I_S = 15 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s}; V_{GS} = 0 \text{ V};$		-	23	46	ns
Q <sub>r</sub>	recovered charge	V <sub>DS</sub> = 15 V; <u>Fig. 16</u>	[1]	-	11	22	nC
t <sub>a</sub>	reverse recovery rise time			-	10.2	-	ns
t <sub>b</sub>	reverse recovery fall time	Ĭ		-	12.6	-	ns
S	softness factor			-	1.2	-	

#### [1] includes capacitive recovery

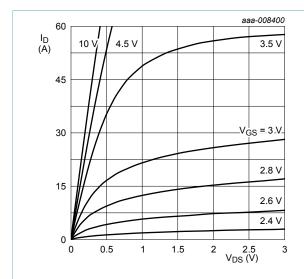


Fig. 7. Output characteristics; drain current as a function of drain-source voltage; typical values



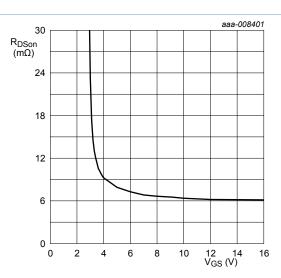


Fig. 8. Drain-source on-state resistance as a function of gate-source voltage; typical values

$$T_j = 25$$
°C;  $I_D = 15A$ 

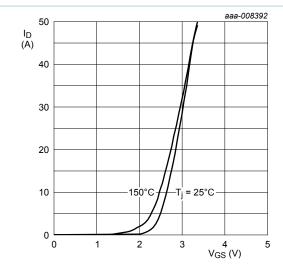


Fig. 9. Transfer characteristics; drain current as a function of gate-source voltage; typical values

 $V_{DS} = 10V$ 

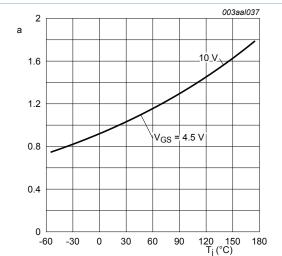


Fig. 11. Normalized drain-source on-state resistance factor as a function of junction temperature

-60

$$a = \frac{R_{DSon}}{R_{DSon (25^{\circ}C)}}$$

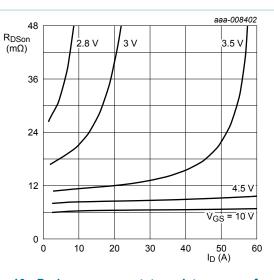


Fig. 10. Drain-source on-state resistance as a function of drain current; typical values

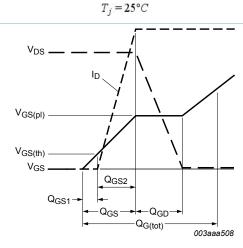


Fig. 12. Gate charge waveform definitions

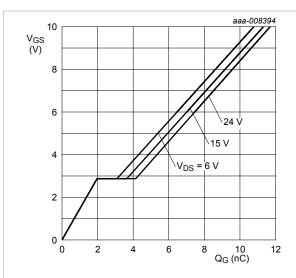


Fig. 13. Gate-source voltage as a function of gate charge; typical values

$$T_j = 25^{\circ}C; I_D = 15A$$

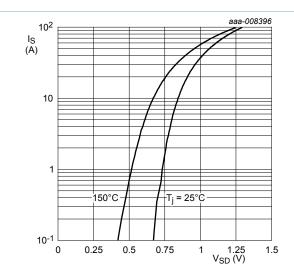


Fig. 15. Source current as a function of source-drain voltage; typical values

$$V_{GS} = 0V$$

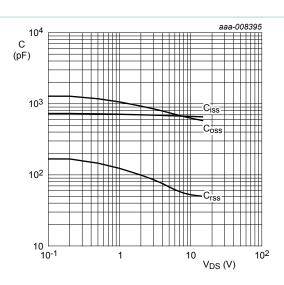


Fig. 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

$$V_{GS} = \mathbf{0}V; \ f = \mathbf{1}MHz$$

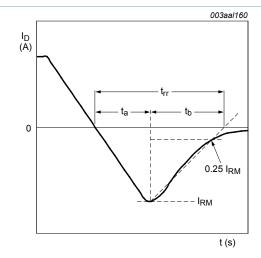
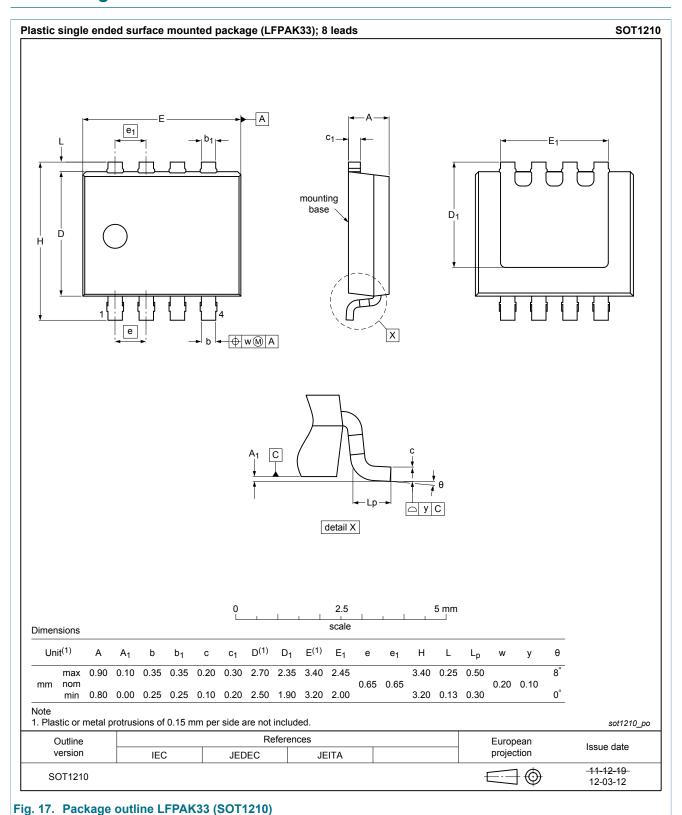


Fig. 16. Reverse recovery timing definition

### 11. Package outline



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### 13. Contents

1	General description	1
2	Features and benefits	1
3	Applications	1
4	Quick reference data	1
5	Pinning information	2
6	Ordering information	2
7	Marking	2
8	Limiting values	3
9	Thermal characteristics	4
10	Characteristics	5
11	Package outline	10
12	Legal information	11
12.1	Data sheet status	11
12.2	Definitions	11
12.3	Disclaimers	11
12.4	Trademarks	12

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13 / 13